

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

Heat Sink Riveted to Memory Module with Upper Slots and Open
Bottom Edge for Air Flow

Application Number :

Confirmation Number:

First Named Applicant: Ren-Kang Chiou

Attorney Docket Number: ML-16

Art Unit:

Examiner:

Search string: (6535387 or 6473306 or 6449156 or 6424532 or 6362966 or 5543660).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6535387	2003-05-18	Summers , et al.	B1	361	704
	2	6473306	2002-10-29	Koseki , et al.	B1	361	704
	3	6449156	2002-09-10	Han , et al.	B1	361	704
	4	6424532	2002-07-23	Kawamura	B1	361	708
	5	6362966	2002-03-26	Ali , et al.	B1	361	728
	6	5543660	1996-08-06	Dombroski	B1	257	707

Signature

Examiner Name	Date